

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4083196

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MASAO TOMIKAWA	09/28/2016
TAKUO WATANABE	09/28/2016
CHUNGSEO LEE	09/05/2016
RECEIVING PARTY DATA	
Name:	TORAY INDUSTRIES, INC.
Street Address:	1-1, NIHONBASHI-MUROMACHI 2-CHOME, CHUO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	103-8666
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15121446
CORRESPONDENCE DATA	
Fax Number:	(215)656-2498
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	215-656-3381
Email:	pto.phil@dlapiper.com
Correspondent Name:	T. DANIEL CHRISTENBURY
Address Line 1:	ONE LIBERTY PLACE
Address Line 2:	1650 MARKET STREET, SUITE 4900
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	TIP-16-1452
NAME OF SUBMITTER:	CAROL CONEY
SIGNATURE:	/cc/
DATE SIGNED:	10/05/2016
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
source=TIP-16-1452#page1.tif	
source=TIP-16-1452#page2.tif	

TIP-16-1452

COMBINED DECLARATION/ASSIGNMENT

WHEREAS, we

Masao Tomikawa of Otsu, Japan
Takuo Watanabe of Otsu, Japan
Chungseo Lee of Gumi, Korea

(hereinafter referred to as "the undersigned"), have made an invention entitled POLYIMIDE RESIN, RESIN COMPOSITION USING SAME, AND LAMINATED FILM identified in International Application No. PCT/JP2015/055222 and US Application No. 15/121,446, (DLA Piper is authorized to insert the Serial No. when known),

the above-identified application was made or authorized to be made by the persons executing this Declaration;

we believe that we are the original joint inventors of a claimed invention in the application;

we hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, Toray Industries, Inc. with offices at 1-1, Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8666 Japan (hereinafter referred to as "assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If

EAST\126992283.1

the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

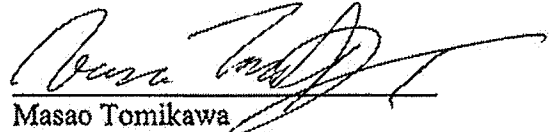
The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the dates set forth below.

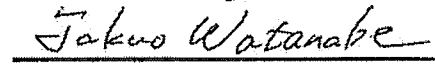
 Sep. 28. 2016
Date

 Sep 28. 2016
Date

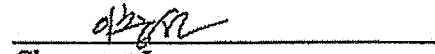
 Sep 05. 2016
Date



Masao Tomikawa



Takuo Watanabe



Chungseo Lee